

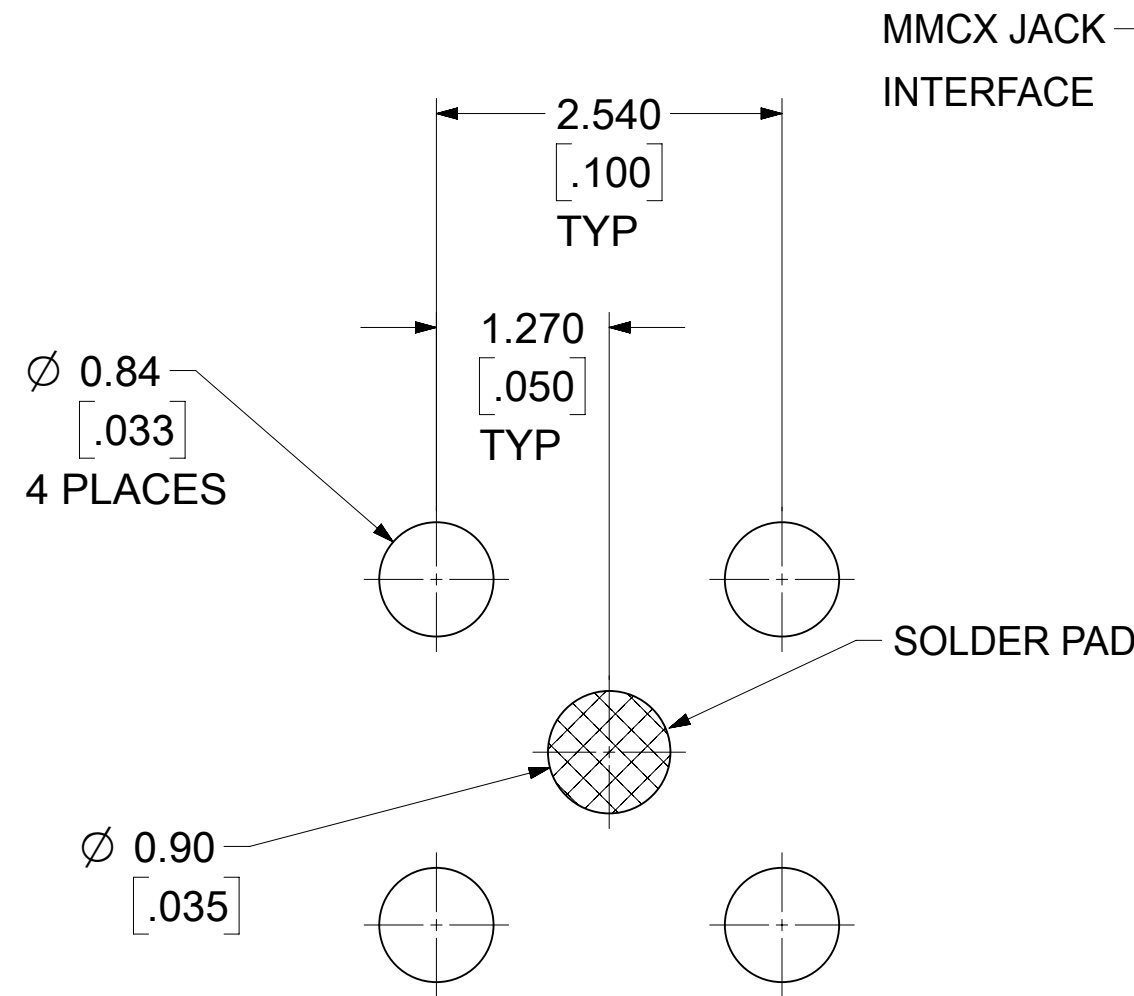
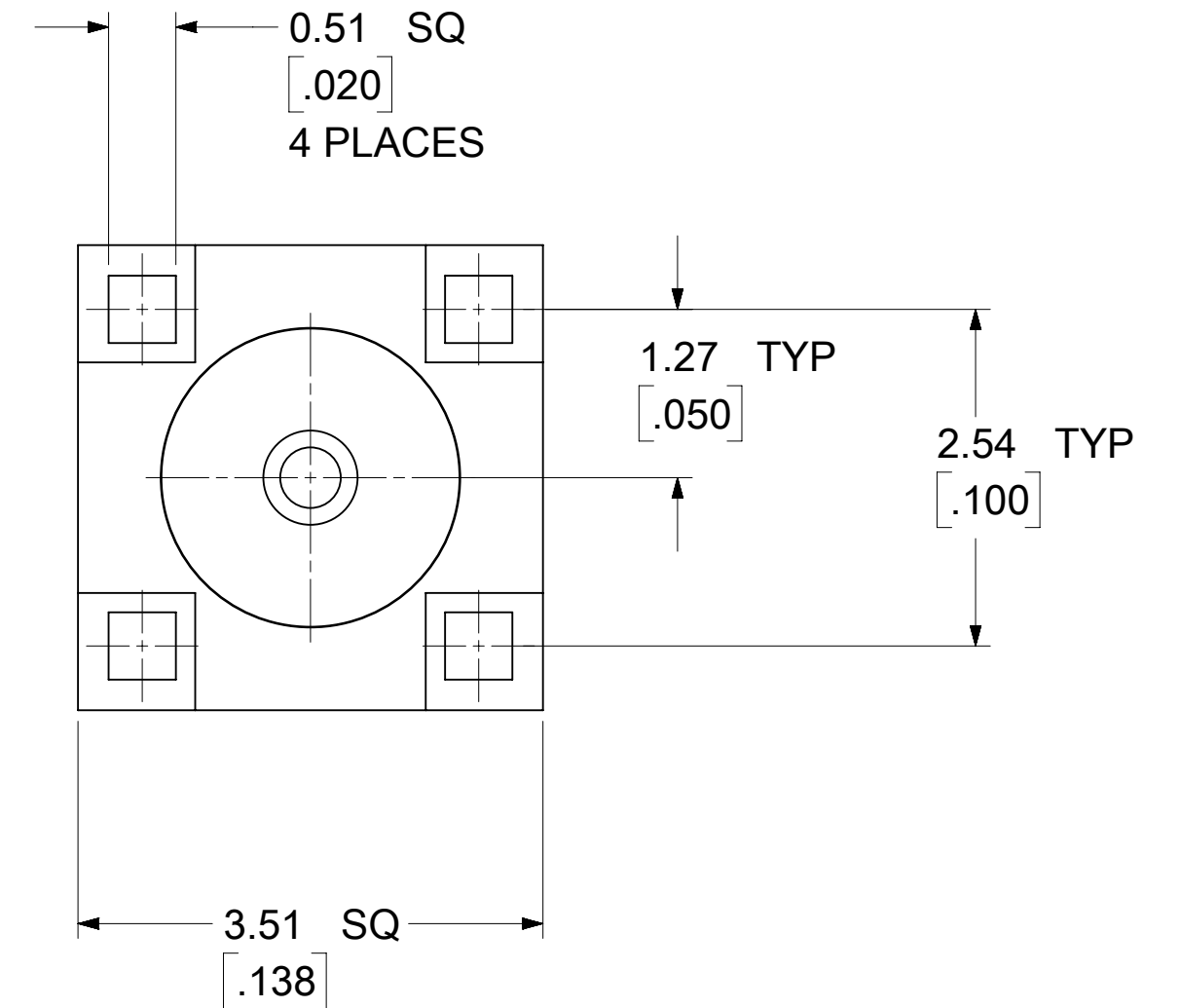
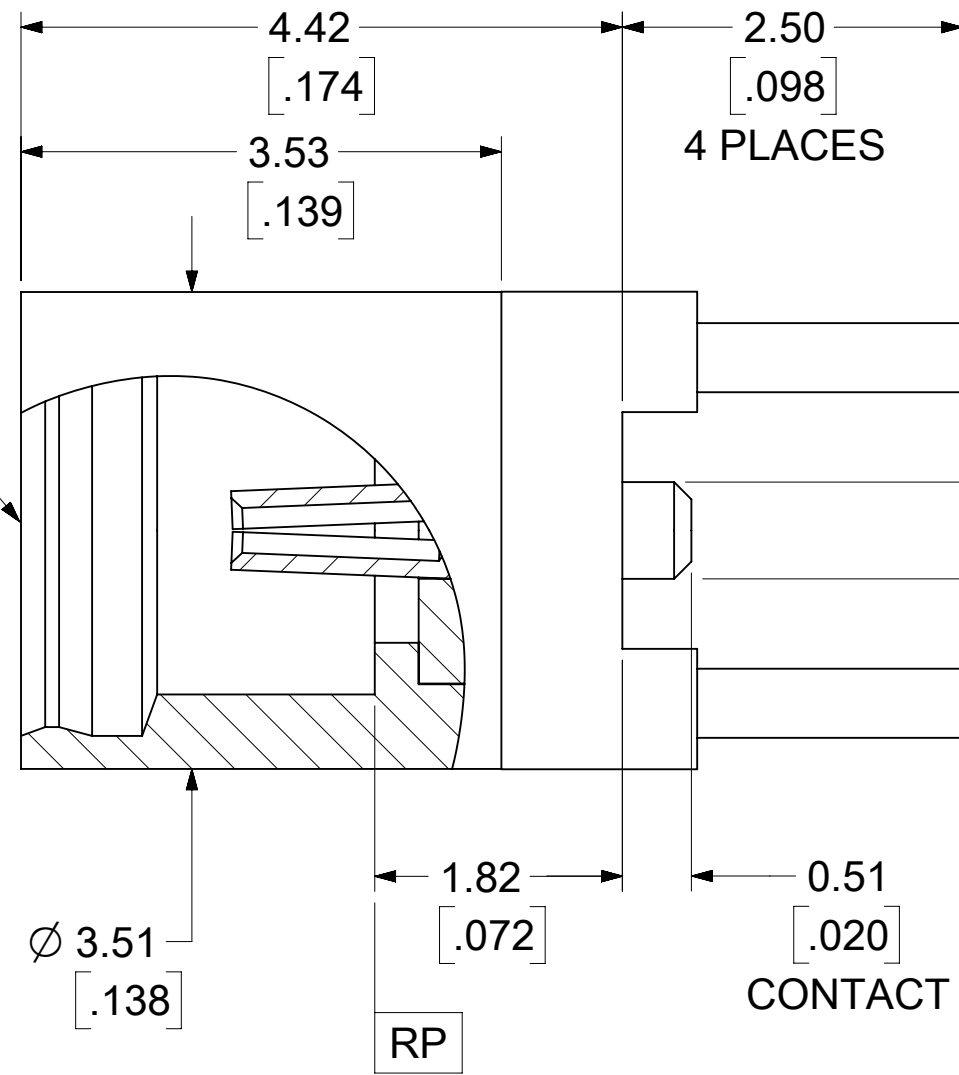
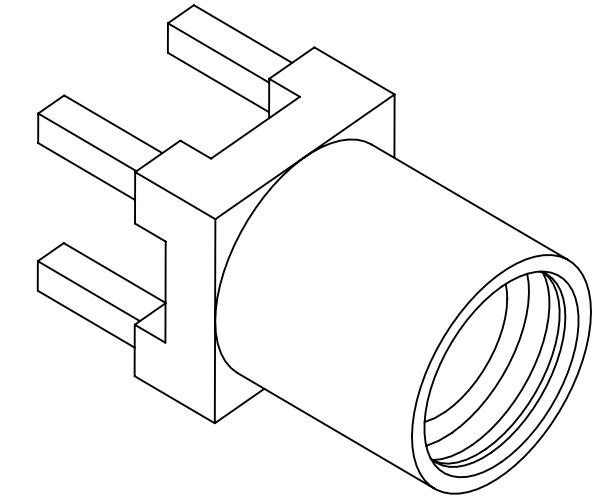
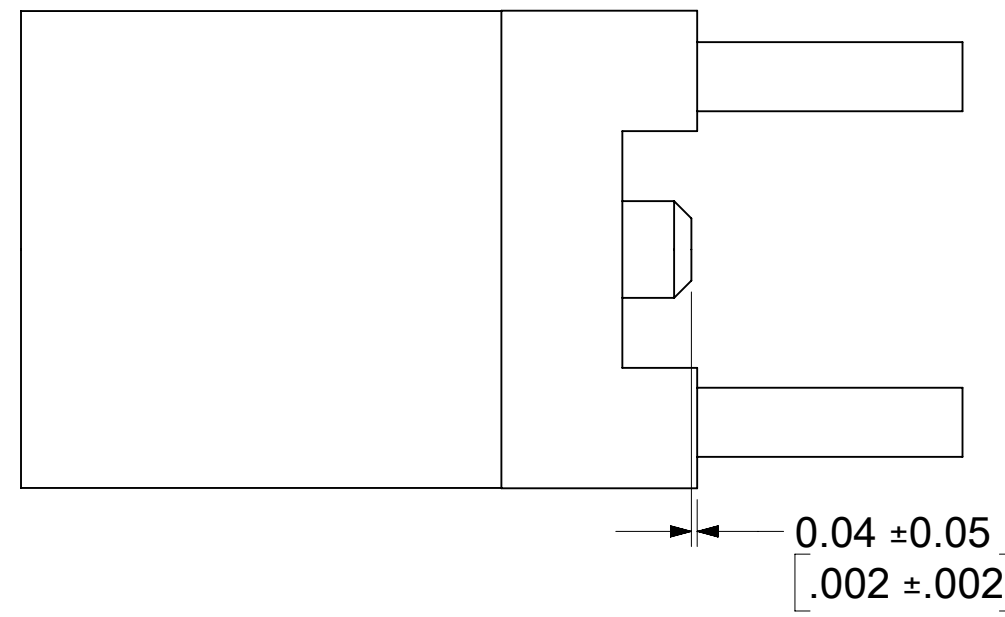
MATERIALS AND FINISHES

BODY BRASS
PLATED GOLD

CENTER CONTACT BERYLLIUM COPPER
PLATED GOLD

INSULATOR TEFLON

PACKING SPEC: SEE 895420040 DRAWING



SUGGESTED PCB LAYOUT

PART NO # 73414-0760

CECC 22 340	INTERFACE
PS-89675-1920	ELECTRO/MECH PER.
SPECIFICATION	DESCRIPTION

FUNCTIONAL SYMBOLS	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		CURRENT REV DESC: EWR-15607-A: ADDED PACKING SPEC ON DRAWING		molex			
	DIMENSION UNITS	SCALE						
FA = 0	MM/INCH	NTS	EC NO: 732954		MMCX JACK STR. FOR PCB PIN IN PIN PASTE MMCX-J			
FC = 0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DRWN: JSU18 2022/12/21					
FD = 0	ANGULAR TOL ± 2.0°		CHK'D: YCHENG 2022/12/26		PRODUCT CUSTOMER DRAWING			
DIVISIONAL SYMBOLS		4 PLACES ±	APPR: YCHENG 2022/12/26					
		3 PLACES ± 0.05	INITIAL REVISION:		DOCUMENT NUMBER			
		2 PLACES ± 0.1	DRWN: ELIN 2015/07/31					SD-73414-076
		1 PLACE ±	APPR: YCHENG 2015/08/10		DOC TYPE			
		0 PLACES ±						DOC PART
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIRD ANGLE PROJECTION		DRAWING		REVISION		
		C-SIZE		SERIES				
				73414		SHEET NUMBER		
DOCUMENT STATUS		P1		RELEASE DATE		GENERAL MARKET		
2022/12/26		01:55:53						